

IN THE CLAIMS:

Please cancel Claim 8 without prejudice or disclaimer of the subject matter recited therein.

Please amend Claims 1-3 as follows.

1. (Currently Amended) A microstructure comprising:
a support substrate;
a movable plate; and
an elastic support portion comprising a first section having at least one concave portion, and second sections having no concave portions, the second sections arranged at both longitudinal ends of the first section and connecting with the movable plate and the support substrate, respectively,

wherein a cross section of the concave portion in a vertical direction to a torsion axis has a substantially V-shape, and

wherein the movable plate is supported by the elastic support portion so that the movable plate can be freely torsion-vibrated to the support substrate about ~~[[a]]~~ the torsion axis.

2. (Currently Amended) The microstructure according to claim 1, wherein a length of the first section is not shorter than a half of the entire length of the elastic support portion in a direction of the torsion-axis ~~direction~~.

3. (Currently Amended) The microstructure according to claim 1, wherein the first section has a third section in which a depth of the concave portion increases as approaching the center of the first section along a direction of the torsion-axis direction, and wherein the third section connects with the second section.

4. (Previously Presented) The microstructure according to claim 1, wherein the support substrate, the elastic support portion, the movable plate and the concave portion are integrally formed of a single-crystal material.

5. (Original) The microstructure according to claim 4, wherein the single-crystal material is single-crystal silicon.

6. (Previously Presented) The microstructure according to claim 5, wherein the elastic support portion is constituted by equivalent planes of a silicon crystal plane.

7. (Previously Presented) The microstructure according to claim 5, wherein the concave portion is constituted by an equivalent plane of a silicon crystal plane.

Claim 8. (Cancelled).

9. (Original) A micro optical deflector comprising the microstructure of claim 1, driving means for relatively driving the support substrate and the movable plate, and a reflection plane formed on the movable plate to reflect light.

10. (Original) An optical apparatus comprising the micro optical deflector of claim 9.

11. (Original) An image display apparatus comprising a light source and a micro optical deflector or a micro optical deflector group in which at least one micro optical deflector of claim 9 for deflecting the light emitted from the light source is set,
wherein at least a part of the light deflected by the micro optical deflector or micro optical deflector group is projected onto an image display body.

12. (Withdrawn) A microstructure fabrication method comprising:
a step of forming mask layers on both faces of a silicon substrate;
a step of removing the mask layer on a first face among the mask layers but leaving the mask layer on contour portions of a support substrate, an elastic support portion and a movable plate;
a step of removing the mask layer at the opposite side of the first face among the mask layers but leaving the mask layer on contour portions of the support substrate, the elastic support portion and the movable plate, and removing the mask layer on a portion for forming a concave portion of the elastic support portion;
a step of dividing the silicon substrate into the support substrate, the elastic support portion and the movable plate and forming a concave portion on the elastic support portion by immersing the silicon substrate in an alkaline aqueous solution to subject the substrate to anisotropic etching; and
a step of removing the mask layer on the silicon substrate.

13. (Withdrawn) A microstructure fabrication method comprising:

- a step of forming mask layers on both faces of a silicon substrate;
- a step of removing the mask layers on the both faces of the silicon substrate but leaving the mask layers on contour portions of a support substrate, an elastic support portion and a movable plate, and removing the mask layer on a portion for forming the concave portion of the elastic support portion;
- a step of dividing the silicon substrate into the support substrate, the elastic support portion and the movable plate and forming a concave portion on the elastic support portion by immersing the silicon substrate in an alkaline aqueous solution to subject the substrate to anisotropic etching, and
- a step of removing the mask layer on the silicon substrate.